imall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

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Switching Diode

Features

- High-Speed Switching Applications
- Lead Finish: 100% Matte Sn (Tin)
- Qualified Reflow Temperature: 260°C
- Extremely Small SOD-523 Package
- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant



Rating	Symbol	Value	Unit
Continuous Reverse Voltage	V _R	100	V
Continuous Forward Current	١ _F	200	mA
Peak Forward Surge Current	I _{FM(surge)}	500	mA
Repetitive Peak Forward Current (Pulse Wave = 1 sec, Duty Cycle = 66%)	I _{FRM}	500	mA
Non-Repetitive Peak Forward Current (Square Wave, $T_J = 25^{\circ}C$ prior to surge) $t = 1 \ \mu s$ $t = 1 \ ms$ $t = 1 \ s$	I _{FSM}	4.0 1.0 0.5	A

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Мах	Unit
Total Device Dissipation, (Note 1) $T_A = 25^{\circ}C$ Derate above 25°C	PD	200 1.57	mW mW/°C
		1.57	mw/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	635	°C/W
Junction and Storage Temperature	T _J , T _{stg}	-55 to 150	°C

1. FR-5 Minimum Pad.



ON Semiconductor®

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MARKING

SOD-523 CASE 502



A6 = Specific Device Code M = Date Code • = Pb-Free Package (Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping†
BAS16XV2T1G	SOD–523 (Pb–Free)	3000 / Tape & Reel
BAS16XV2T5G	SOD–523 (Pb–Free)	8000 / Tape & Reel
SBAS16XV2T1G	SOD–523 (Pb–Free)	3000 /T ape & Reel

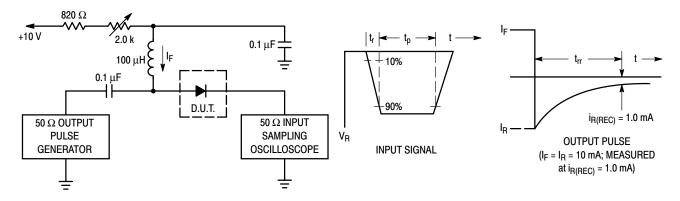
+For information on tape and reel specifications, including part orientation and tape sizes, please

refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

BAS16XV2

ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS	· · · · · ·		-	-
Reverse Voltage Leakage Current $(V_R = 100 \text{ V})$ $(V_R = 75 \text{ V}, T_J = 150^{\circ}\text{C})$ $(V_R = 25 \text{ V}, T_J = 150^{\circ}\text{C})$	I _R		1.0 50 30	μΑ
Reverse Breakdown Voltage (I _{BR} = 100 μA)	V _(BR)	100	-	V
Forward Voltage $(I_F = 1.0 \text{ mA})$ $(I_F = 10 \text{ mA})$ $(I_F = 50 \text{ mA})$ $(I_F = 150 \text{ mA})$	VF	- - -	715 855 1000 1250	mV
Diode Capacitance ($V_R = 0$, f = 1.0 MHz)	CD	-	2.0	pF
Forward Recovery Voltage $(I_F = 10 \text{ mA}, t_r = 20 \text{ ns})$	V _{FR}	-	1.75	V
Reverse Recovery Time $(I_F = I_R = 10 \text{ mA}, R_L = 50 \Omega)$	t _{rr}	_	6.0	ns
Stored Charge (I _F = 10mA to V _R = 5.0V, R _L = 500 Ω)	Q _S	_	45	рС



Notes: 1. A 2.0 k Ω variable resistor adjusted for a Forward Current (I_F) of 10 mA.

2. Input pulse is adjusted so $I_{R(peak)}$ is equal to 10 mA.

3. t_p » t_{rr}

Figure 1. Recovery Time Equivalent Test Circuit

BAS16XV2

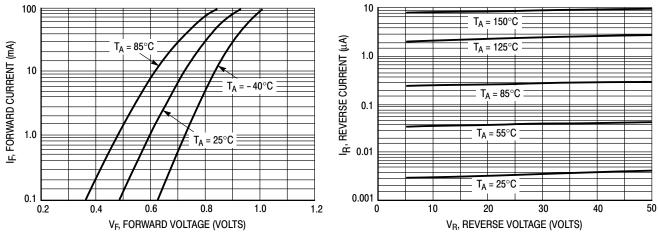
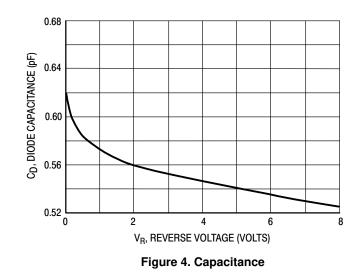


Figure 2. Forward Voltage

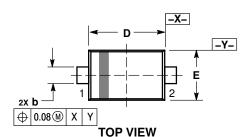
Figure 3. Leakage Current

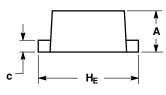


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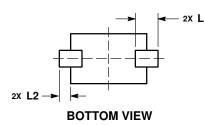
PACKAGE DIMENSIONS

SOD-523 CASE 502 ISSUE E







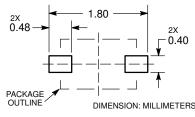


NOTES:

- I. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 CONTROLLING DIMENSION: MILLIMETERS
- CONTROLLING DIMENSION: MILLIMETERS.
 MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH.
- MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
- DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PRO-TRUSIONS, OR GATE BURRS.

	MILLIMETERS		
DIM	MIN	NOM	MAX
Α	0.50	0.60	0.70
b	0.25	0.30	0.35
С	0.07	0.14	0.20
D	1.10	1.20	1.30
E	0.70	0.80	0.90
ΗE	1.50	1.60	1.70
L	0.30 REF		
L2	0.15	0.20	0.25

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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